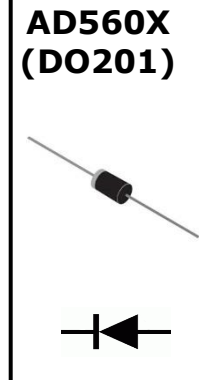


60V 5A ULTRA LOW VF TMOS Schottky

Characteristics Summary

Characteristics	Values	Units
IF(AV)	5	A
VRRM	60	V
VF TYP @ 3A, TJ = 25°C	0.47	V
@ 5A, TJ = 25°C	0.54	V
IR _{MAX} @ TJ = 25°C	25	uA



Features

- Reduced low forward voltage drop (VF) ; better efficiency and cooler operation.
- Reduced high temperature reverse leakage; Increased reliability against thermal runaway failure in high temperature operation.
- Softest, fast switching capability
- 150°C Operating Junction Temperature
- Lead Free Finish, RoHS Compliant

Typical Applications

Device optimized for low forward voltage drop to suitable efficiency in general rectification applications.

· Boost Diode, Blocking Diode, Rectifier, Recirculating Diode

Maximum Ratings Characteristics - (TA = 25°C unless otherwise specified)

Parameter	Symbol	Values	Units
DC Blocking Voltage	V _{RM}	60	V
Working Peak Reverse Voltage	V _{RWM}		V
Peak Repetitive Reverse Voltage	V _{RRM}		V
Average Rectified Forward Current (Rated VR-20Khz Square Wave) – 50% duty cycle	I _D	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms	I _{FSM}	60	A
Typical Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	30	°C / W
Operating Junction Temperature	T _J	-55 to +150	°C
Storage Junction Temperature	T _{STG}	-55 to +150	

Note 1 : FR-4 PCB, 2 oz Copper. Minimum recommended pad layout

Electrical Characteristics - (TA = 25°C unless otherwise specified)

Parameter	Test Conditions		Symbol	Typ.	Max.	Units
Forward Voltage	IF = 2 A	TJ = 25°C	VF*	0.44	0.48	V
	IF = 3 A			0.47	0.51	
	IF = 5 A			0.54	0.59	
	IF = 5 A	TJ = 125°C		0.50	-----	
Reverse Current	VR = 60V	TJ = 25°C	IR*	9	25	uA
		TJ = 125°C		4	10	mA

* Short duration pulse test used to minimize self-heating effect.

Characteristics Curves

($T_A = 25^{\circ}\text{C}$ unless otherwise specified)

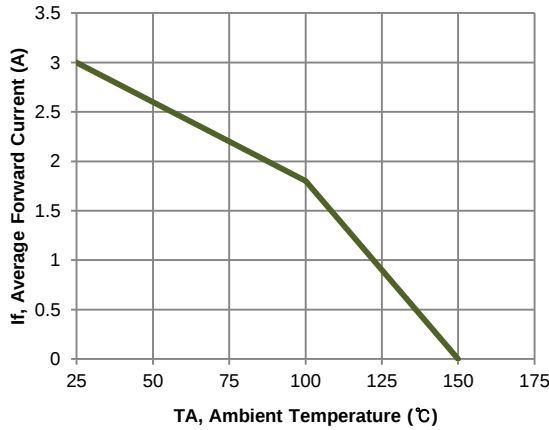


Figure 1 : DC Forward Current Derating

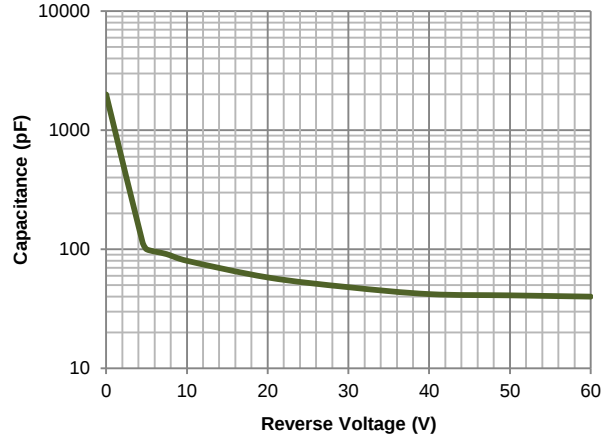


Figure 2 : Typical Junction Capacitance

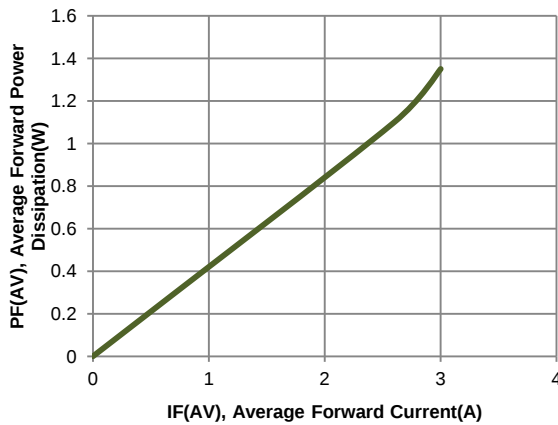


Figure 3. Forward Power Dissipation

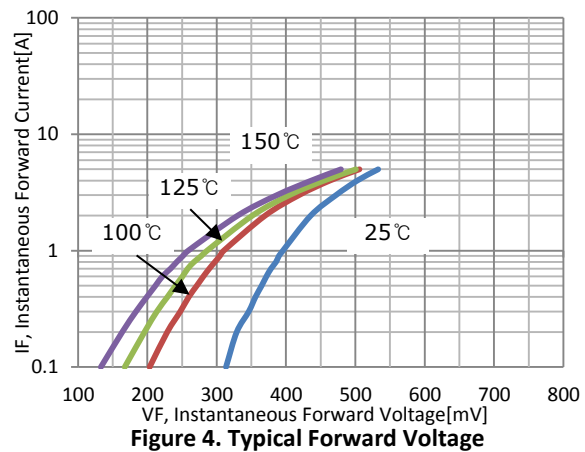


Figure 4. Typical Forward Voltage

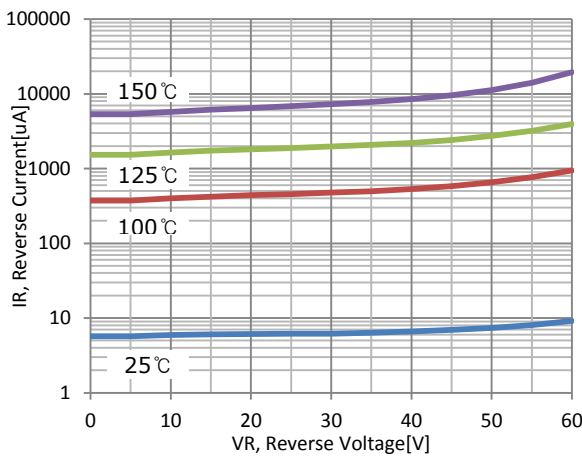
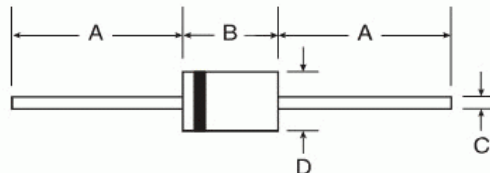


Figure 5. Typical Reverse Current

Ordering Information

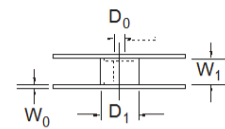
Part No	Package	Packing	Finish	Halogen	Packing Unit
AD560X	DO-201	13" Reel & Tape	Sn	Free	1,200ea

Package Dimension

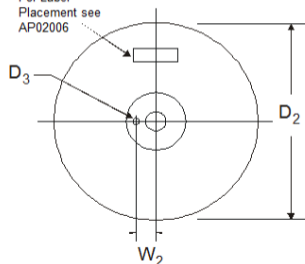


DO-201AD		
Dim	Min	Max
A	25.40	—
B	7.20	9.50
C	1.20	1.30
D	4.80	5.30
All Dimensions in mm		

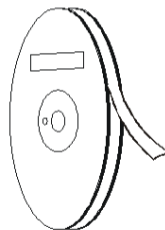
Reel Packing Method



For Label Placement see AP02006



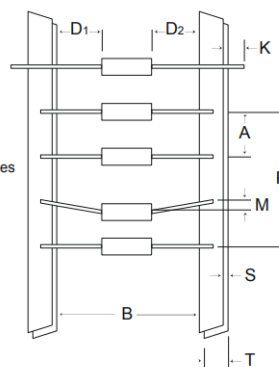
Direction of Unreeling



PRODUCT REEL			
Description	Symbol	Specification(mm)	Alternate(mm)
Arbor Hole Diameter	D0	16.6 ± 0.50	30.0 ± 0.50
Core Diameter (O.D)	D1	81.0 Typical	81.0 Typical
Reel Diameter	D2	345.0 ± 15.0	260.0 ± 15.0
Drive Hole Diameter	D3	9.5 ± 0.5	9.5 ± 0.5
Material Thickness	W0	2.0 – 4.0	2.0 – 4.0
Reel Width	W1	80.0 ± 5.0	65.0 ± 5.0
Drive/ Arbor Hole Spacing	W2	27.5 ± 0.5	27.5 ± 0.5

Core material: plastic (blue/black) or metal (neutral)
Reel material: corrugated board or plastic (blue or black)

Dimensions A, M, K, P, S, & T apply to both sides



REEL AND AMMO PACK TAPING SPECIFICATIONS		
Description	Symbol	Specification (mm)
Component Pitch	A	10.0 ± 0.5
Inside Tape Spacing	B	52.4 ± 1.5
Lead to Lead Eccentricity	D1 - D2	1.4 max
Lead Extension	K	0.8 max
Lead Bending	M	1.2 max
Cumulative Pitch	P	±1.5 per 6 pitch
Exposed Adhesive	S	0.8 max
Tape Width	T	6.0 ± 0.4
Empty Spaces		< 0.1%
Polarity Marking	All polarized components shall be oriented in the same direction. The cathode tape shall be colored, and the anode tape shall be white or light beige. Anode end must face label-side of reel. See AP02006 for label placement.	

Revision History

No	Date	Contents
0	2016-10-25	Initial Brief Datasheet Release

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